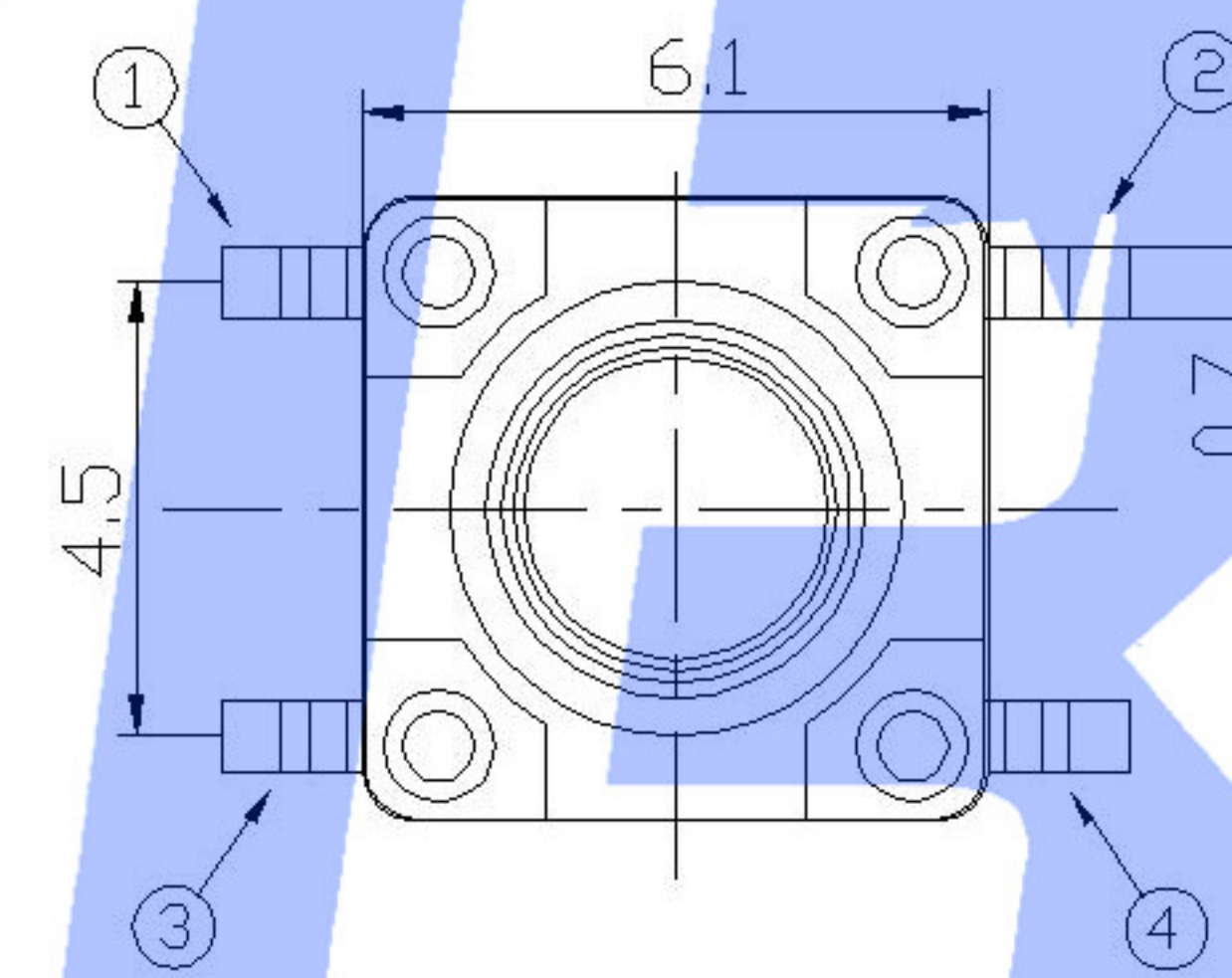
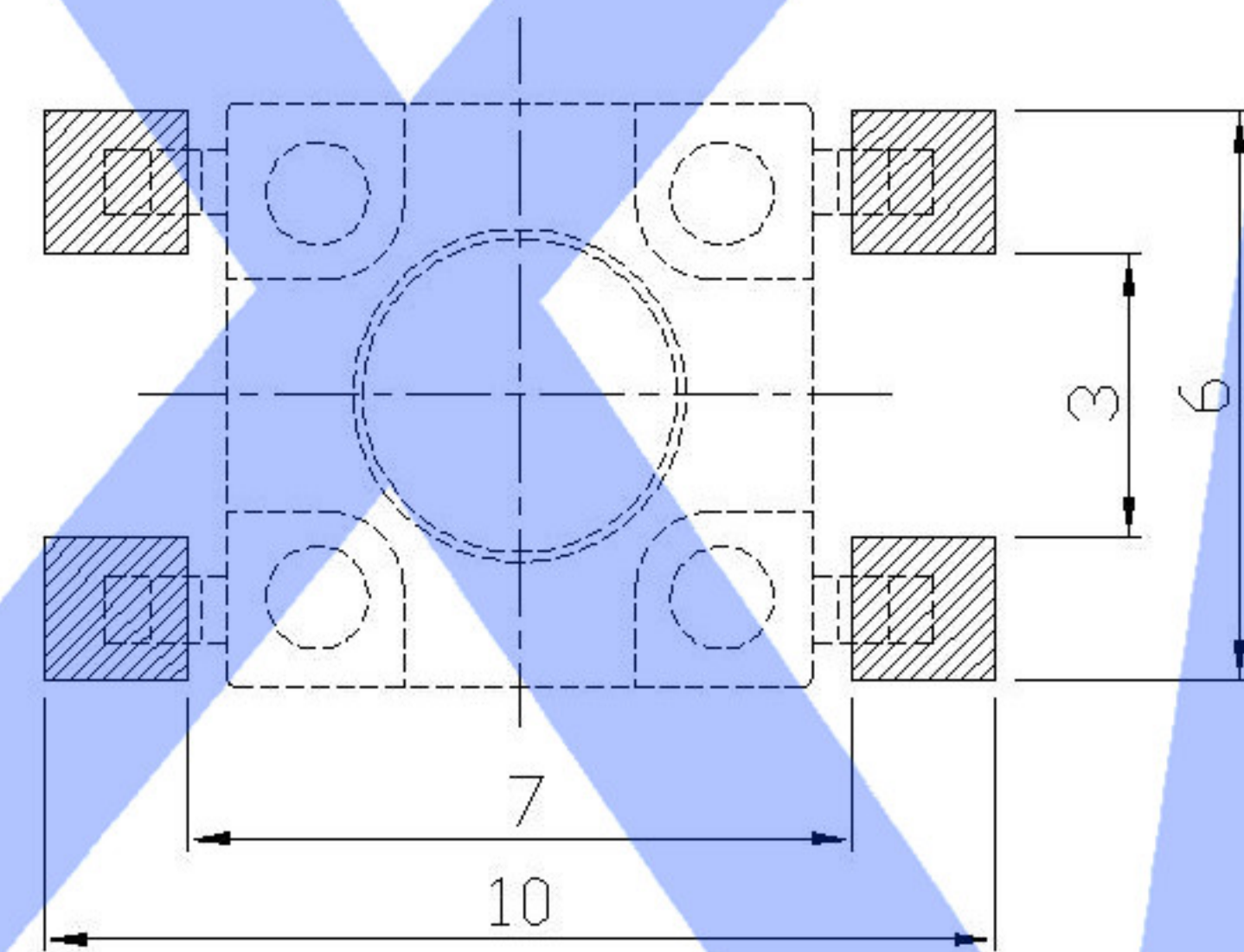
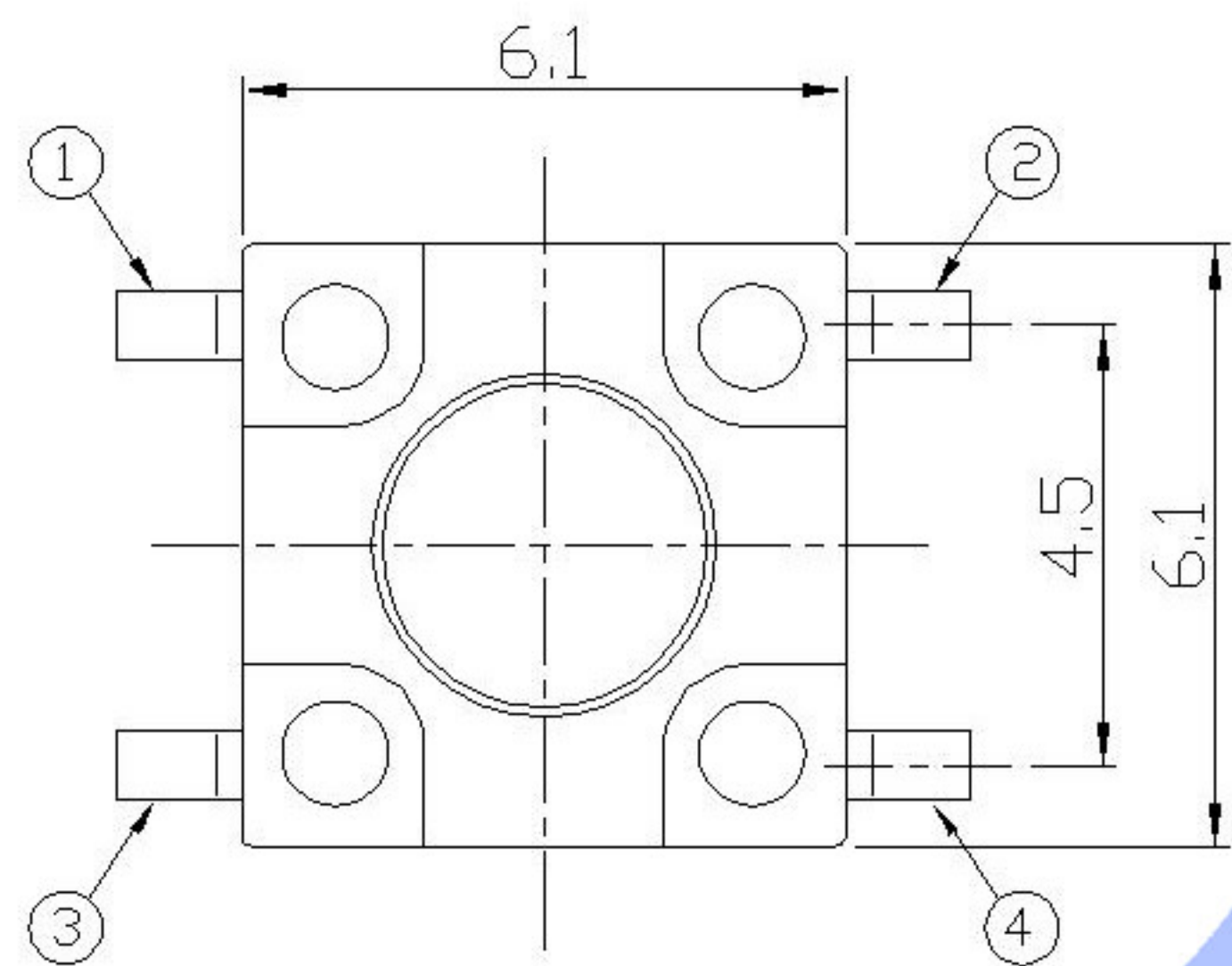
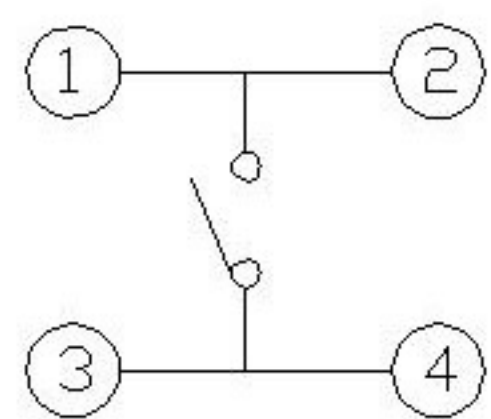


Code-X	H
L	9.5
M	10.0
N	10.5
O	11.0
P	11.5
Q	12
R	12.5
S	13.0
T	13.5
U	14.0
V	15.0
W	15.5
X	16
Y	16.5
Z	17
18	18
19	19

P.C.B MOUNTING PATTERN DIMENSION  
The following soldering patterns are recommended for reflow soldering



CIRCUIT DIAGRAM



Code-X	H
A	4.3
B	4.5
C	5.0
D	5.5
E	6.0
F	6.5
G	7.0
H	7.5
I	8.0
J	8.5
K	9.0

SPECIFICATION

Contact Rating: 50mA, 12V DC  
 Contact Resistance: 100mΩ max  
 Insulation Resistance: 100mΩ min, 500V DC  
 Dielectric Strength: 250V AC/1minute  
 Travel: 0.25mm  
 Operating Temp: -25°C~+80°C  
 Storage Temp: -30°C~+80°C

PAPT NO	TS-FS66T-X-X
Operating Force	A: 100gf B: 160gf C: 260gf
Height	Code-X

ITEM	PAPT NAMF	TER,NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	—	4	Brass (0.30t)	Plating silvering	—
④	Contact	—	1	F.ag/Sus	Natural	—
③	Base	—	1	Pa46		—
②	Cover	—	1	Pa46		—
①	Keystake	—	1	Pa46		—

MARK	DESCRIPTION	DATE	REVISED	APPROVED	units: mm	DSND	DATE	SCALE: N/A	MODEL TYPE: TACT SWITCH
Δ X					tolerance:	DWN	DATE	VIEW:	PART NO.:
					X.X ±0.2mm	CHKD	DATE	UNIT: mm	DWG NO.:
					X.XX ±0.1mm	APPD	DATE	SIZE: A4	TS-FS66T-X-X
					X.XXX ±0.05mm	XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT: 1.0g
REVISIONS						UNSPECIFIED TOLERANCES			SHEET: 1/1
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn									REVISION: A0